



Click [here](#) for the 3D model.

Dimensions

| | |
|-----------|------------------|
| Chip Size | 1206 |
| L | 3.2mm +/-0.2mm |
| W | 1.6mm +/-0.2mm |
| T | 0.78mm +/-0.10mm |
| B | 0.5mm +/-0.25mm |

Packaging Specifications

| | |
|--------------------|--------------------------|
| Packaging | T&R, 330mm, Plastic Tape |
| Packaging Quantity | 10000 |

General Information

| | |
|------------------|--|
| Series | ESD SMD Comm COG |
| Style | SMD Chip |
| Description | SMD, MLCC, Temperature Stable, Electro Static Discharge, Class I |
| Features | Temperature Stable, Low ESR, Class I |
| RoHS | Yes |
| Termination | Tin |
| Marking | No |
| AEC-Q200 | No |
| Component Weight | 15 mg |
| Shelf Life | 78 Weeks |
| MSL | 1 |

Specifications

| | |
|--|------------------------|
| Capacitance | 4700 pF |
| Measurement Condition | 1 kHz 1.0Vrms |
| Capacitance Tolerance | 5% |
| Voltage DC | 100 VDC |
| ESD Level per AEC-Q200 | 25,000 V ESD Level |
| Dielectric Withstanding Voltage | 250 VDC |
| Temperature Range | -55/+125°C |
| Temperature Coefficient | COG |
| Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC) | 30 ppm/C, 1kHz 1.0Vrms |
| Dissipation Factor | 0.1% 1 kHz 1.0Vrms |
| Aging Rate | 0% Loss/Decade Hour |
| Insulation Resistance | 100 GOhms |

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